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28. (once amended) A PVD component produced by the method comprising inducing a sufficient amount of stress in the component to increase magnetic pass through flux exhibited by the component compared to pass through flux exhibited prior to inducing the stress.

29. (once amended) A sputter component produced by the method comprising: unidirectionally first cold working a component blank to at least about an 80% reduction in cross-sectional area;

heat treating the cold worked component blank at least at about a minimum recrystallization temperature of the component blank; and

inducing a sufficient amount of stress in the heat treated component to increase magnetic pass through flux exhibited by the heat treated component compared to pass through flux exhibited prior to inducing the stress.

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(once amended) A sputter target produced by the method comprising: unidirectionally first cold rolling a target blank consisting essentially of nickel to at least about an 85% reduction in cross-sectional area;

heat treating the cold rolled target blank at a temperature between about 427 °C (800 °F) to about 482 °℃ (900 °F) for less than about 60 minutes; and

second cold rolling the heat treated target blank to a reduction in cross-sectional area of about 10% of the heat treated component, at least about 70% of a surface area at least within selected boundaries of a surface of the second cold rolled target blank exhibiting a (200) texture.